

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

ltc1264cn#pbf

(Engineering Calculation)

PDIP

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**TOTAL MASS (g) : 1.589983**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.009084	1000000	5713.26855469		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.458357	975000	288277.9375		
		Iron (Fe)	7439-89-6	0.011283	24000	7096.30224609		
		Phosphorus (P)	7723-14-0	0.000141	300	88.68019104		
		Zinc (Zn)	7440-66-6	0.000329	700	206.920455933		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.470110</b>	<b>1000000</b>	<b>295669.8125</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.037246	1000000	23425.4179688		
		<b>External Plating Total:</b>				<b>0.037246</b>	<b>1000000</b>	<b>23425.4179688</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.003761	1000000	2365.43408203		
<b>Internal Plating Total:</b>				<b>0.003761</b>	<b>1000000</b>	<b>2365.43408203</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.002044	750000	1285.54833984		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000681	250000	428.30645752		
<b>Die Attach Total:</b>				<b>0.002725</b>	<b>1000000</b>	<b>1713.8548584</b>		
Encapsulation	FILLED EPOXY RESIN	Resin (EP)		0.143937	135000	90527.3828125		
		Bromine (Br)	40039-93-8	0.007463	7000	4693.76123047		
		Silica (SiO2)	60676-86-0	0.895608	840000	563281.5		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.013861	13000	8717.703125		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.005331	5000	3352.8659668		
		<b>Encapsulation Total:</b>				<b>1.066200</b>	<b>1000000</b>	<b>670573.25</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000857	1000000	538.999511719		
					<b>TOTAL MASS (g) :</b>	<b>1.589983</b>		